



## **SPECIFICATION**

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL05C471JB5NNNC
- Description : CAP, 470pF, 50V, ±5%, C0G, 0402

A. Samsung Part Number

	<u>CL</u>	<u>05</u> <u>C</u>	<u>471</u> <u>J</u>	<u>B</u> 5	<u>N N</u>	<u>N C</u>	
	1	23	4 5	6 7	89	10 11	
Samsung Multi-layer Ceramic Capacitor							
<ol> <li>Size</li> </ol>	0402 (inch co	-		) ± 0.05	mm	W: 0.5 ± 0	.05 mm
③ Dielectric	C0G		(8)	Inner ele	ctrode	Ni	
<ul><li>④ Capacitance</li></ul>	470 pF		٢	Termina		Cu	
5 Capacitance	±5 %			Plating		Sn 100%	(Pb Free)
tolerance			9	Product		Normal	
Rated Voltage	50 V		10	Special		Reserved	for future use
⑦ Thickness	$0.5 \pm 0.05$	mm	1	Packagiı	ng	Cardboard	Type, 7" reel

## B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition			
Capacitance	Within specified tolerance	1M±10% 0.5~5Vrms			
Q	1000 min				
Insulation	10,000Mohm or 500Mohm ⋅ μF	Rated Voltage 60~120 sec.			
Resistance	Whichever is Smaller				
Appearance	No abnormal exterior appearance	Microscope (×10)			
Withstanding	No dielectric breakdown or	300% of the rated voltage			
Voltage	mechanical breakdown				
Temperature	C0G				
Characterisitcs	(From -55 $^\circ\!\!\!\!\mathrm{C}$ to 125 $^\circ\!\!\!\mathrm{C}$ , Capacitance change shoud be within ±30PPM/ $^\circ\!\!\!\mathrm{C}$ )				
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.			
of Termination	terminal electrode				
Bending Strength	Capacitance change :	Bending to the limit (1mm)			
	within $\pm 5\%$ or $\pm 0.5$ pF whichever is larger	with 1.0mm/sec.			
Solderability More than 75% of terminal surface		SnAg3.0Cu0.5 solder			
	is to be soldered newly	245±5℃, 3±0.3sec.			
		(preheating : 80~120 $^{\circ}$ for 10~30sec.)			
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.			
Soldering heat	within $\pm 2.5\%$ or $\pm 0.25$ pF whichever is larger				
	Tan δ, IR : initial spec.				

	Performance	Test condition			
Vibration Test	Capacitance change :	Amplitude : 1.5mm			
	within $\pm 2.5\%$ or $\pm 0.25$ pF whichever is larger	From 10Hz to 55Hz (return : 1min.)			
	Tan δ, IR : initial spec.	2hours $\times$ 3 direction (x, y, z)			
Moisture	Capacitance change :	With rated voltage			
Resistance	within $\pm 7.5\%$ or $\pm 0.75$ pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs			
	Q : 200 min				
	IR : 500Mohm or 25Mohm $\cdot \mu F$				
	Whichever is Smaller				
High Temperature	Capacitance change :	With 200% of the rated voltage			
Resistance	within $\pm 3\%$ or $\pm 0.3$ pF whichever is larger	Max. operating temperature			
	Q : 350 min	1000+48/-0hrs			
	IR : 1000Mohm or 50Mohm $\cdot \mu F$				
	Whichever is Smaller				
Temperature	Capacitance change :	1 cycle condition			
Cycling	within $\pm 2.5\%$ or $\pm 0.25$ pF whichever is larger	Min. operating temperatur $\rightarrow$ 25 °C			
	Tan δ, IR : initial spec.	$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^\circ\!\mathrm{C}$			
		5 cycle test			

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max )

\* For the more detail Specification, Please refer to the Samsung MLCC catalogue.